LINEAR TECHNOLOGY MATERIALS DECLARATION

LT3009ESC8-1.5#TRPBF		(Engineering Calculation)		SC70		
(printed on: 7/26/2011 6:12:34 AM)					TOTAL MASS (g):	0.01042012
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000464	1000000	44529.24
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.003442	975000	330322.5
		Iron (Fe)	7439-89-6	8.50E-05	24000	8157.296
		Phosporus (P)	7723-14-0	1.00E-06	300	95.96819
		Zinc (Zn)	7440-66-6	2.00E-06	700	191.9364
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		0.00353	1000000	338767.7
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.00340812	1000000	327071.1
		External Plating Total:		0.00340812	1000000	327071.1
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	2.30E-05	1000000	2207.269
		Internal Plating Total:		2.30E-05	1000000	2207.269
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000289	750000	27734.81
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Antimony (Sb)	7440-36-0	0	0	0
		Resin (EP)		9.60E-05	250000	9212.946
		Die Attach Total:		0.000385	1000000	36947.75
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000147	58000	14107.32
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.002261	890000	216984.1
		Antimony	1309-64-4	0	0	0
		Trioxide (Sb2O3)				
		Metal Hydroxid		0.000127	50000	12187.96
		Carbon Black (C)	1333-86-4	5.00E-06	2000	479.8409
		Encapsulation Total:		0.00254	1000000	243759.2
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	7.00E-05	1000000	6717.773
Estimated						
			TOTAL MASS (g):			0.01042012